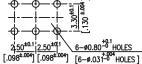
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RoHS Compliant

Specification

General tolerances : ±0.2mm

Diagram 0 Q 3.50 000 Q 1 0 <u>1.50</u> [.059] CIRCUIT <u>2.00</u> .079 TRAVEL Ĵ, <u>1.50</u> [.059] F <u>3.50</u> .138] 2.40 .094 [.098 047 3.00 0.60 2.50 2.50 [.098] [.098]

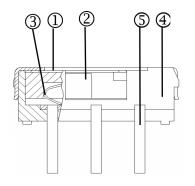


P.C.B. LAYOUT (VIEW FROM THE DIRECTION A)

Dimensions : Millimetres (Inches)

Item	Description	Q'ty	Materials	Treatment
1	Cover		Stainless Steel	
2	Stem		High - Temp Thermoplastic Nylon UL94V - 0	Molded Black
3	Contact	1	Phosphor Bronze	With Silver Plating
4	Base		High-Temp Thermoplasitc LCP	Molded Black
5	Terminal		Brass	With Silver Plating





1. Style

This specification describes "DUAL IN-LINE PACKAGE SWITCHES" mainly used as signal switch of electric devices with the general requirements of mechanical and electrical characteristics.

- 1.1 Operating Temperature Range : -10°C to +60°C
- 1.2 Storage Temperature Range : -20°C to +75°C
- 1.3 The shelf life of product is within 6 months.
- 2. Current Range:
- 2.1 Non-Switching : 100mA, 50V DC
- 2.2 Switching : 0.1A , 12V DC
- 3. Type of Actuation: Actuated by sliding
- 4. Test Sequence:

Item	Description	Test Conditions	Requirements				
Appea	Appearance						
1	Visual Examination	By visual examination check without any out pressure & testing.	There shall be no defects that affect the serviceability of the product.				
Electr	Electric Performance						
2	Contact Resistance	 To be measured between the two terminals associated with each switch pole. Measurements shall be made with a 1kHz shall current contact resistance meter. 	60mΩ max. (initial)				
3	Insulation Resistance	500V DC, 1 minute ± 5 sec.	100MΩ Min.				
4	Withstanding Voltage	500V AC (50Hz or 60 Hz) shall be applied between all the adjacent terminals and between the terminal and the frame for 1 minute.	No dielectric breakdown shall be occurred				
5	Capacitance	1 MHz ±10 kHz	5 pF max.				
6	Bounce	Applied in the direction of operation.	200±150gf				

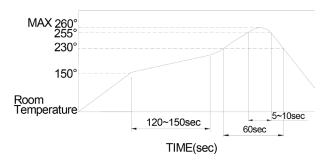


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Mechanical Perfprmance						
7	Stop Strength	 (a)The static load of 2 kg shall be applied in the operating direction of the control unit for 15 seconds. (b)The static load of 1 kg shall be applied in the right angle of the operating direction unit for 15 seconds. 	There shall be no sign of electrical function out of order or damage.			
8	Soldering Heat Resistance	 Soldering Temperature TEMP TIME 260°C±5°C 3±1 sec. Duration of Solder Immersion: 5±1 sec. Frequency of Soldering Process: 2 times max. 	As shown in item 2~6			
9	Solderability	 THROUGH HOLE TYPE Soldering Temperature:245±3°C Lead-Free solder: M705E JIS Z 3282 Class A (Tin 96.5%, Silver 3%, Copper 0.5%) (Flux: 5-10 seconds. (Duration of solder Immersion: 5±1 sec. (SMT TYPE SEE PAGE 3/4 	No anti-soldering and the coverage of dipping into solder must more than 75% was requested.			
Durat	oility					
10	Operation Life	Measurements shall be made following the test set forth below: 1)25 mA, 24V DC resistive load 2)Rate of Operation: 15~20 cycles/ minute 3)Cycle of Operation: 10,000 cycles.	 As shown in item 3,4 Contact Resistance: 120mΩ max. (final-after test) 			
Weatl	ner-Proof					
11	Resistance Low Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made : 1. Temperature : -20°C ±2°C 2. Time: 96 hours	1. As shown in item 2~5 2. Operating Force: Within ±30% of item 6			
12	Resistance High Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made : 1) Temperature : 85°C±2°C 2) Time: 96 hours	1.As shown in item 3~6 2. Contact Resistance: 120mΩ max.			
13	Resistance Humidity	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made : 1) Temperature : 40°C±2°C 2) Relative Humidity :90~95% 3) Time: 96 hours	1.As shown in item 4,6 2.Contact Resistance: $120m\Omega$ max. 3.Insulation Resistance : $10M\Omega$ min.			



Soldering Conditions



The condition mentioned above is the temperature on the Cu foil of the P.C.B surface. There are cases where board's
temperature greatly differs from switch's surface temperature depending on board's material, size, thickness, etc. Care,
therefore, should be used not to allow switch's surface temperature to exceed 260°C.

Manual Soldering
 Soldering Temperature

Continuous Soldering Time

Max.350°C Max. 5 seconds

Part Number Table

Description	Part Number
Slide Switch, Through Hole, 2P2T	MPLSS22-V

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